

SECTION II—CLAIMS

1.-13. (Canceled)

14. (Currently Amended) A process of forming a micro electromechanical (MEMS) package comprising:

~~providing a semiconductor device including an active surface;~~

~~providing a conveyance with at least one embedded MEMS device disposed therein; and~~

coupling a first MEMS device to an active surface of a semiconductor device using a first contact array;

providing a conveyance including a second MEMS device disposed therein and including a via extending through the entire thickness of the conveyance; and

supporting the conveyance over the active surface using a plurality of electrical contacts in a second contact array, wherein the ~~at least one embedded~~ second MEMS device communicates electrically to the semiconductor device via at least one of the contacts in the second contact array and wherein the first MEMS device is positioned within the via.

15. (Currently Amended) The process according to claim 14, wherein the second ~~at least one embedded~~ MEMS device is selected from a switch, a capacitor, an inductor, an oscillator, a power supply, and combinations thereof.

16.-17. (Canceled)

18. (Currently Amended) The process according to claim 14, ~~wherein the conveyance comprises a via disposed therein, the process further comprising:~~

~~providing at least one detached MEMS device in a first structure;~~

~~accommodating the at least one detached MEMS device upon the active surface;~~

providing a sealing structure on the semiconductor device; and

disposing the sealing structure in a manner sufficient to isolate ~~at least one~~ of the ~~at least one detached~~ the first MEMS device.

19. (Original) The process according to claim 14 further comprising:

forming an integrated package comprising the semiconductor device and the conveyance.

20. (Canceled)

21. (Currently Amended) The process according to claim ~~[[20]]~~ 19 further comprising:

encapsulating the ~~detached~~ first MEMS device and the conveyance to form an integrated package.

22. (Currently Amended) The process according to claim 14 further comprising:

encapsulating the semiconductor device to form an integrated package, wherein the ~~at least one detached~~ first MEMS device is accommodated upon the semiconductor device.

23. (Currently Amended) A process comprising:

~~providing a semiconductor device;~~

~~accommodating a detached micro electromechanical structure (MEMS)
device upon the semiconductor device;~~

coupling a first MEMS device to an active surface of a semiconductor
device using a first contact array;

providing a conveyance including a second MEMS device disposed
therein and including a via extending through the entire thickness of the
conveyance; and

supporting ~~[[a]]~~ the conveyance over ~~[[an]]~~ the active surface using a
plurality of electrical contacts in a second contact array, wherein the ~~conveyance~~
~~surrounds the detached MEMS device and the detached~~ second MEMS device
communicates electrically to the semiconductor device via at least one of the
contacts in the second contact array, and wherein the first MEMS device is
positioned within the via; and

contacting encapsulation material with at least one of the semiconductor
device, the first ~~detached~~ MEMS device, and the conveyance to form an
integrated MEMS package.

24. (Currently Amended) ~~The process according to claim 23, further comprising:~~

~~embedding the detached MEMS device in the conveyance.~~

The process according to claim 23, wherein the first MEMS device is
selected from a switch, a capacitor, an inductor, an oscillator, a power supply, and
combinations thereof.

25. (Currently Amended) The process according to claim 23, further comprising:

providing a sealing structure; and

interposing the sealing structure upon the semiconductor device in a manner sufficient to isolate ~~at least one of the~~ first ~~at least one detached~~ MEMS device.

26.-30. (Canceled)